



N 沟道增强型场效应晶体管

N-CHANNEL MOSFET

FHP50N06A

### 主要参数 MAIN CHARACTERISTICS

ID	50 A
VDSS	60 V
Rdson-typ (@Vgs=10V)	12mΩ
Qg-typ	40nC

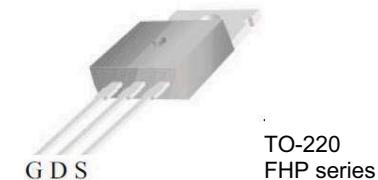
### 用途 APPLICATIONS

逆变电源	Power management for inverter systems
DC-DC转换器和功率开关	DC-DC converter and switch mode power supplies

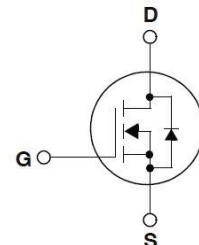
### 产品特性 FEATURES

低栅极电荷	Low gate charge
低 Crss (典型值 130pF)	Low Crss (typical 130pF )
开关速度快	Fast switching
100%经过雪崩测试	100% avalanche tested
高抗 dv/dt 能力	Improved dv/dt capability
RoHS 产品	RoHS product

### 封装形式 Package



### 等效电路 Equivalent Circuit



### 绝对最大额定值 ABSOLUTE RATINGS (Tc=25°C)

项目 Parameter	符号 Symbol	数值 Value	单位 Unit
		FHP50N06A	
最高漏极—源极直流电压 Drain-Source Voltage	VDS	60	V
连续漏极电流* Drain Current -continuous *	I <sub>D</sub> (T <sub>c</sub> =25°C)	50	A
	I <sub>D</sub> (T <sub>c</sub> =100°C)	35	A
最大脉冲漏极电流 (注 1) Drain Current – pulse (note 1)	I <sub>DM</sub>	200	A
最高栅源电压 Gate-Source Voltage	V <sub>GS</sub>	±25	V
单脉冲雪崩能量 (注 2) Single Pulsed Avalanche Energy (note 2)	E <sub>A</sub> S	145	mJ
雪崩电流 (注 1) Avalanche Current (note 1)	I <sub>AR</sub>	13	A
重复雪崩能量 (注 1) Repetitive Avalanche Current (note 1)	E <sub>AR</sub>	5	mJ
二极管反向恢复最大电压变化速率 (注 3) Peak Diode Recovery dv/dt (note 3)	dv/dt	5.0	V/ns
耗散功率 Power Dissipation	P <sub>D</sub> (T <sub>c</sub> =25°C)	50	W
	-Derate above 25°C	0.33	W/°C
最高结温及存储温度 Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55~+175	°C
引线最高焊接温度 Maximum Lead Temperature for Soldering Purposes	T <sub>L</sub>	300	°C

\*漏极电流由最高结温限制

\*Drain current limited by maximum junction temperature

## 电特性 ELECTRICAL CHARACTERISTICS

项目 Parameter	符号 Symbol	测试条件 Tests conditions	最小 Min	典型 Typ	最大 Max	单位 Units	
<b>关态特性 Off -Characteristics</b>							
漏一源击穿电压 Drain-Source Voltage	BVDSS	Id=250μA, Vgs=0V	60	-	-	V	
击穿电压温度特性 Breakdown Voltage Temperature Coefficient	ΔBVdss/Δ TJ	Id=250μA, referenced to 25°C	-	0.06	-	V/°C	
零栅压下漏极漏电流 Zero Gate Voltage Drain Current	Idss	Vds=60V, Vgs=0V, Tc=25°C	-	-	1	μA	
		Vds=48V, Tc=125°C	-	-	10	μA	
栅极体漏电流 Gate-body leakage current	IGSS (F/R)	Vds=0V, Vgs =±25V	-	-	±100	nA	
<b>通态特性 On-Characteristics</b>							
阈值电压 Gate Threshold Voltage	VGS(th)	Vds = VGS , Id=250μA	2.0	3.0	4.0	V	
静态导通电阻 Static Drain-Source On-Resistance	Rds(ON)	Vgs =10V , Id=25A	-	12	15	mΩ	
正向跨导 Forward Transconductance	gfs	Vds = 20V, Id=25A (note 4)	-	65	-	S	
<b>动态特性 Dynamic Characteristics</b>							
栅电阻 Gate Resistance	Rg	f=1.0MHz, VDS OPEN	-	1.7	-	Ω	
输入电容 Input capacitance	Ciss	Vds=25V, Vgs =0V, f=1.0MHz	-	2150	-	pF	
输出电容 Output capacitance	Coss		-	200	-		
反向传输电容 Reverse transfer capacitance	Crss		-	130	-		
<b>开关特性 Switching Characteristics</b>							
延迟时间 Turn-On delay time	td(on)	VDS=30V, Id=25A, RG=6Ω VGS =10V (note 4, 5)	-	30	-	ns	
上升时间 Turn-On rise time	tr		-	20	-	ns	
延迟时间 Turn-Off delay time	td(off)		-	120	-	ns	
下降时间 Turn-Off Fall time	tf		-	25	-	ns	
栅极电荷总量 Total Gate Charge	Qg	VDS =48V , Id=25A , VGS =10V (note 4, 5)	-	40	-	nC	
栅一源电荷 Gate-Source charge	Qgs		-	10	-	nC	
栅一漏电荷 Gate-Drain charge	Qgd		-	13	-	nC	
<b>漏一源二极管特性及最大额定值 Drain-Source Diode Characteristics and Maximum Ratings</b>							
正向最大连续电流 Maximum Continuous Drain -Source Diode Forward Current	Is		-	-	50	A	
正向最大脉冲电流 Maximum Pulsed Drain-Source Diode Forward Current	ISM		-	-	200	A	
正向压降 Drain-Source Diode Forward Voltage	Vsd	Vgs=0V, Is=25A	-	0.82	1.3	V	
反向恢复时间 Reverse recovery time	trr	Vgs=0V, Is=25A ,dI/dt=100A/μs (note 4)	-	40	-	ns	
反向恢复电荷 Reverse recovery charge	Qrr		-	45	-	nC	

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## 热特性 THERMAL CHARACTERISTIC

项目 Parameter	符号 Symbol	最大值 Max	单位 Unit
结到管壳的热阻 Thermal Resistance, Junction to Case	R <sub>th(j-c)</sub>	1.7	°C/W
结到环境的热阻 Thermal Resistance, Junction to Ambient	R <sub>th(j-A)</sub>	62.5	°C/W

注释:

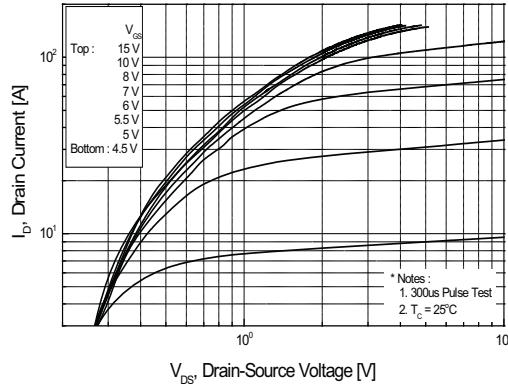
- 1: 脉冲宽度由最高结温限制
- 2: L=1mH, I<sub>AS</sub>=13A, V<sub>DD</sub>=48V, R<sub>G</sub>=25 Ω,起始结温 T<sub>J</sub>=25°C
- 3: I<sub>SD</sub> ≤ 50A, di/dt ≤ 300A/μs, V<sub>DD</sub>≤BV<sub>DSS</sub>,起始结温 T<sub>J</sub>=25°C
- 4: 脉冲测试: 脉冲宽度 ≤300μs,占空比≤2%
- 5: 基本与工作温度无关

Notes:

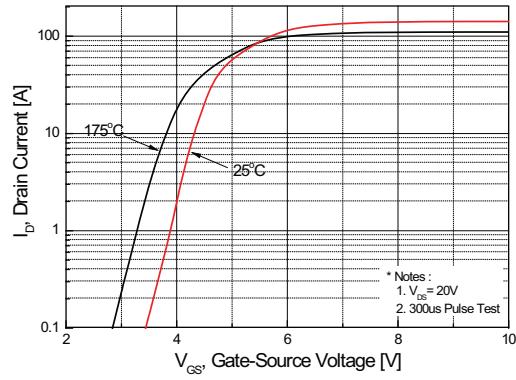
- 1: Pulse width limited by maximum junction temperature
- 2: L=1mH, I<sub>AS</sub>=13A, V<sub>DD</sub>=48V, R<sub>G</sub>=25 Ω, Starting T<sub>J</sub>=25°C
- 3: I<sub>SD</sub> ≤ 50A, di/dt ≤ 300A/μs, V<sub>DD</sub>≤BV<sub>DSS</sub>, Starting T<sub>J</sub>=25°C
- 4: Pulse Test: Pulse Width ≤300μs, Duty Cycle≤2%
- 5: Essentially independent of operating temperature

## Typical Characteristics

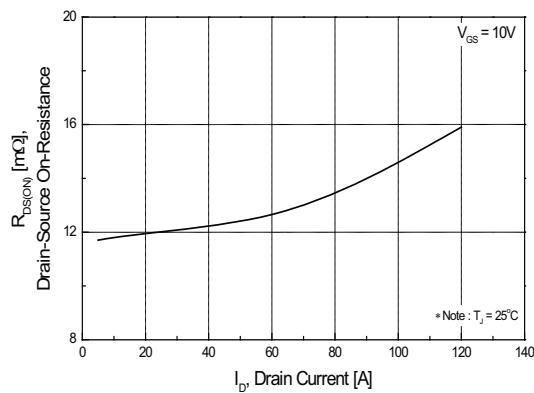
### 典型特性曲线



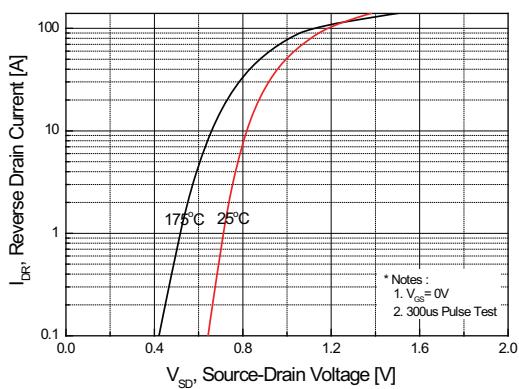
**Figure 1. On Region Characteristics**



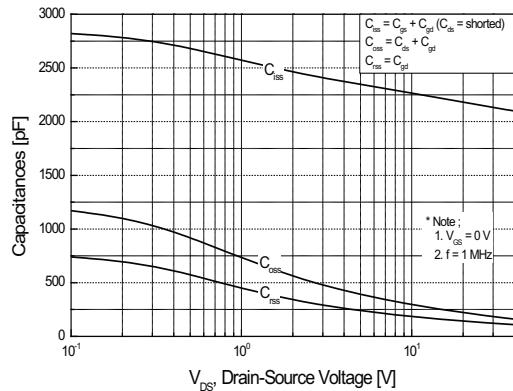
**Figure 2. Transfer Characteristics**



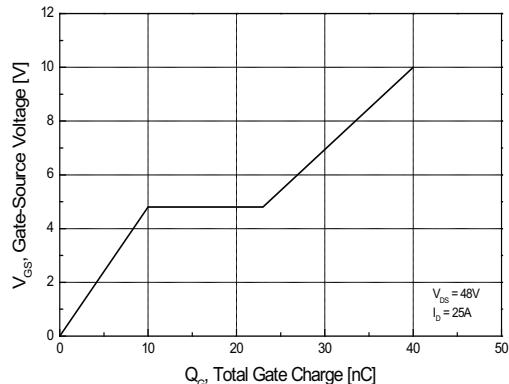
**Figure 3. On Resistance Variation vs. Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**



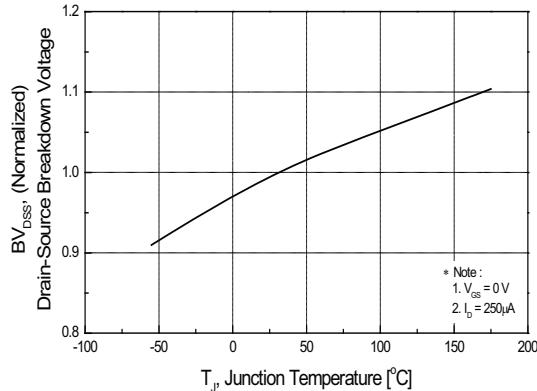
**Figure 5. Capacitance Characteristics**



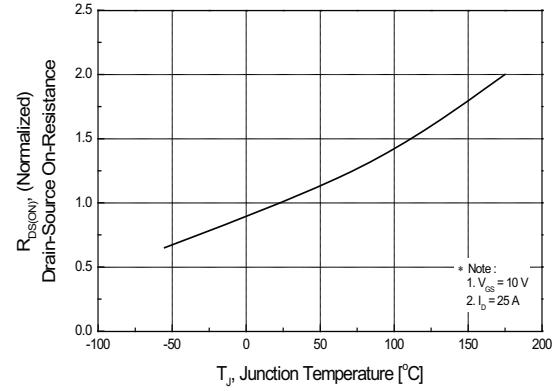
**Figure 6. Gate Charge Characteristics**

## Typical Characteristics (continued)

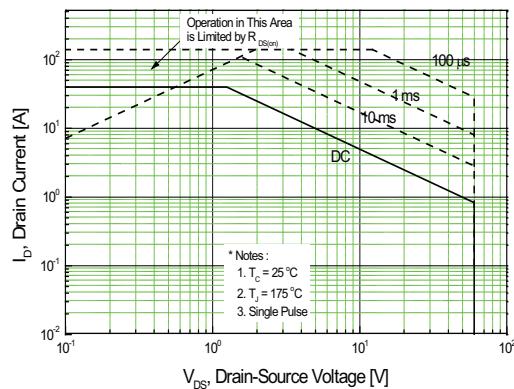
### 典型特性曲线 (续)



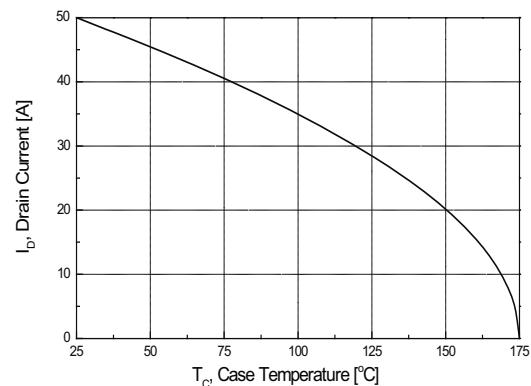
**Figure 7. Breakdown Voltage Variation vs Temperature**



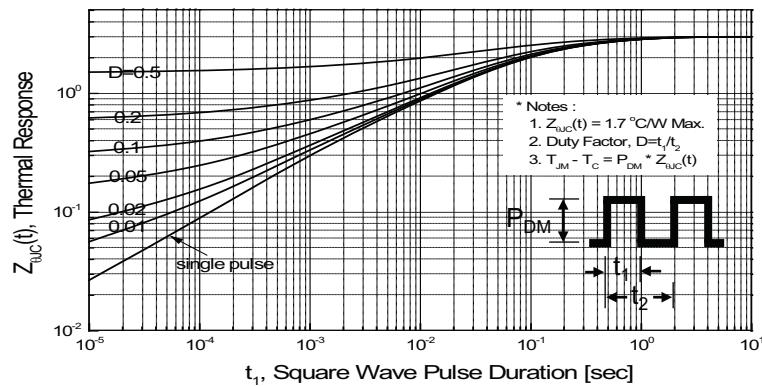
**Figure 8. On-Resistance Variation vs Temperature**



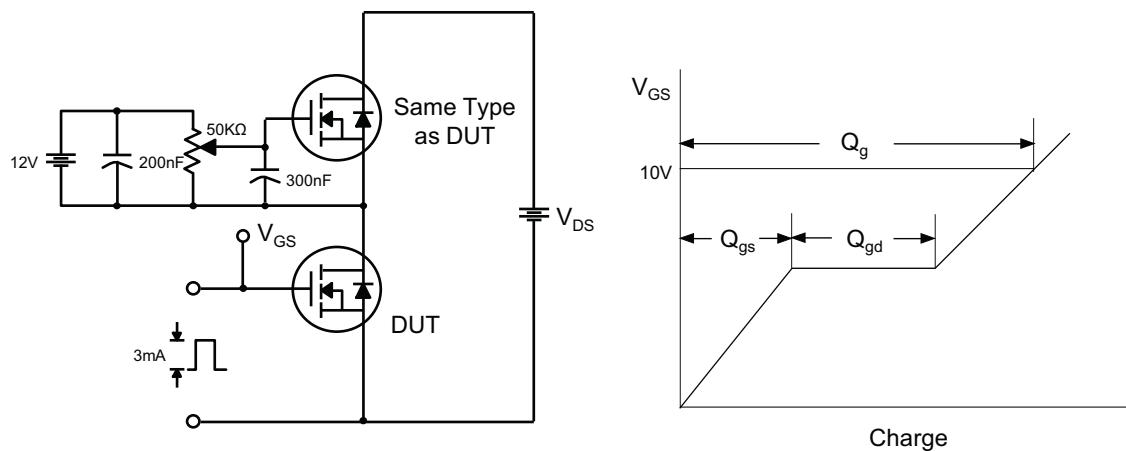
**Figure 9. Maximum Safe Operating Area**



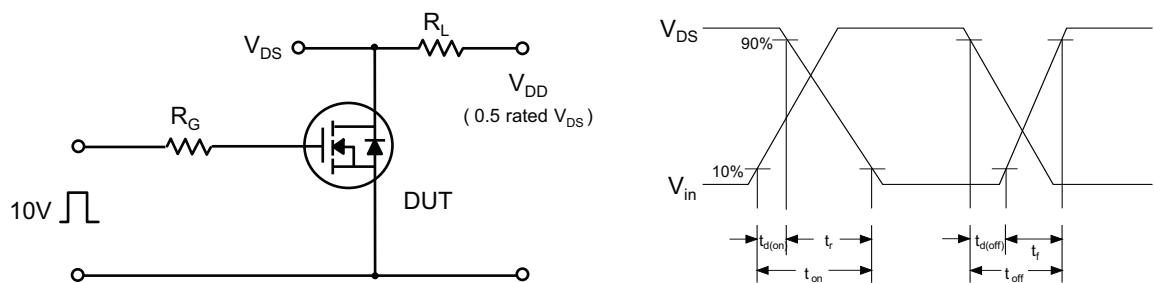
**Figure 10. Maximum Drain Current vs Case Temperature**



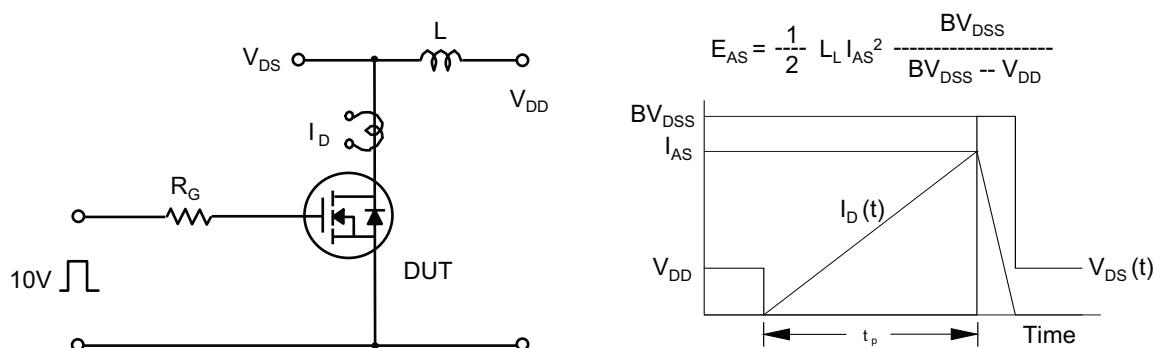
**Figure 11. Transient Thermal Response Curve**



**Fig 12. Gate Charge Test Circuit & Waveform**



**Fig 13. Resistive Switching Test Circuit & Waveforms**



**Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms**

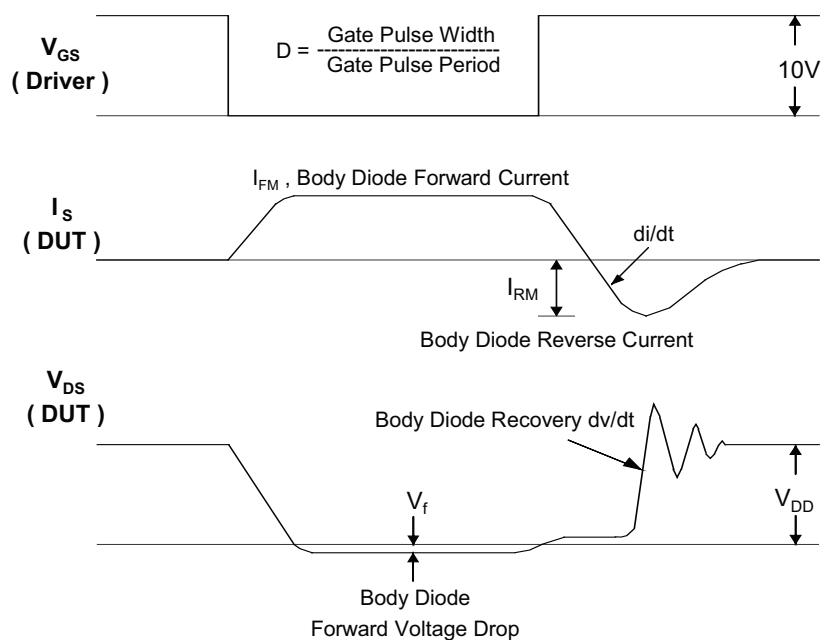
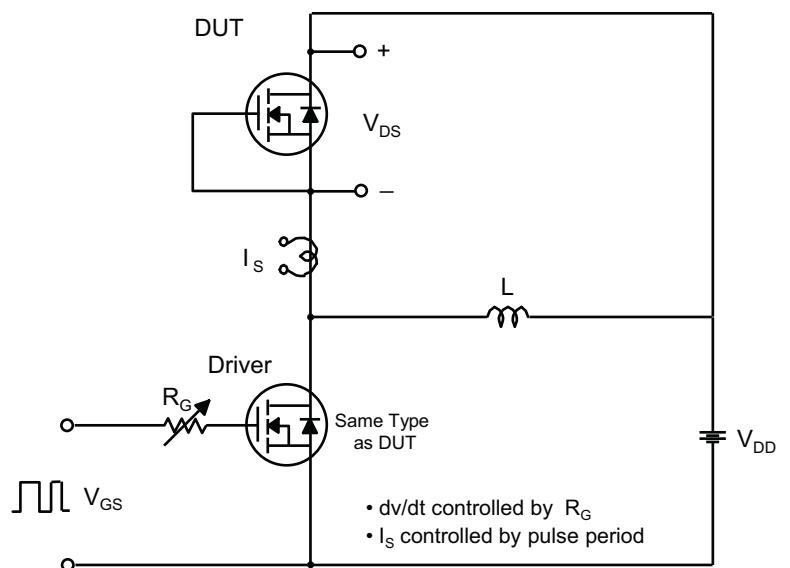
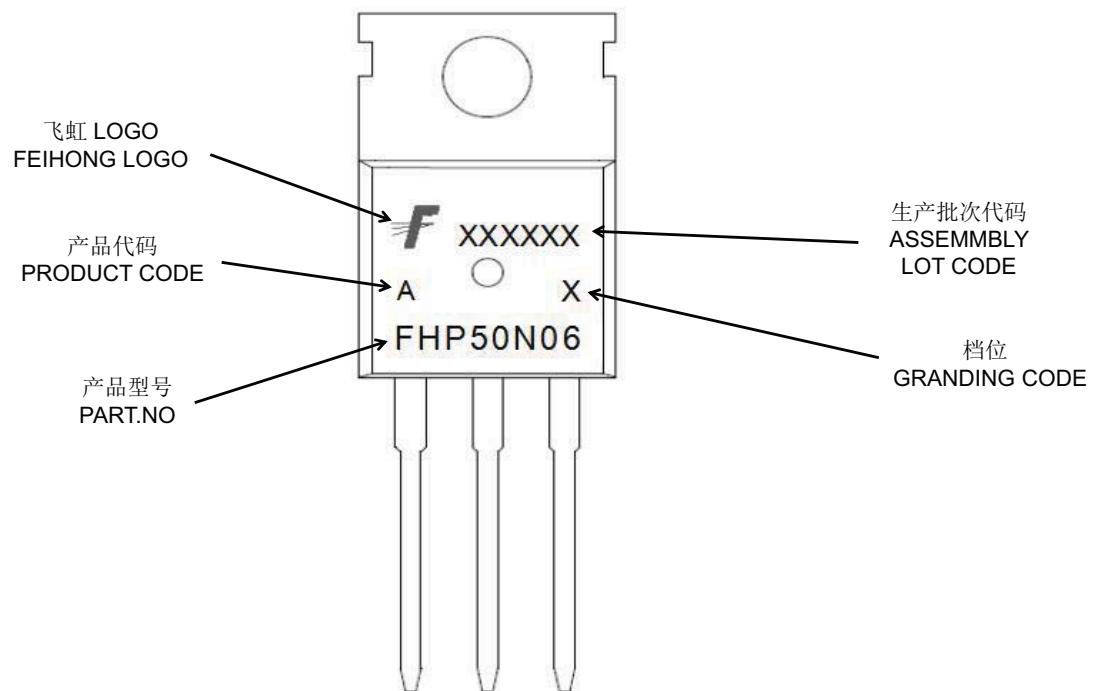


Fig 15. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms

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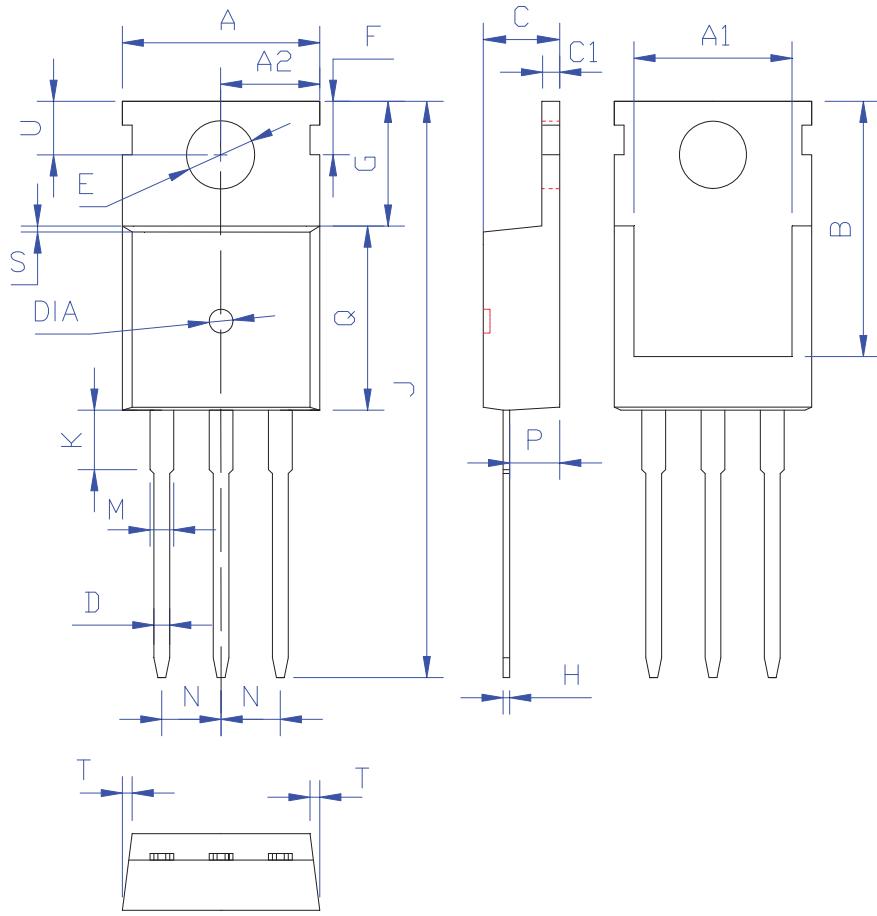
**印记 Marking:**



外形尺寸:

Package Dimension:

TO-220



DIM	MILLIMETERS
A	10.00±0.30
A1	8.00±0.30
A2	5.00±0.30
B	13.20±0.40
C	4.50±0.20
C1	1.30±0.20
D	0.80±0.20
E	3.60±0.20
F	3.00±0.30
G	6.60±0.40
H	0.50±0.20
J	28.88±0.50
K	3.00±0.30
M	1.30±0.30
N	Typical 2.54
P	2.40±0.40
Q	9.20±0.40
S	0.25±0.15
T	0.25±0.15
U	2.80±0.30
DIA	宽 1.50±0.10 深 0.50 MAX

(Unit: mm)